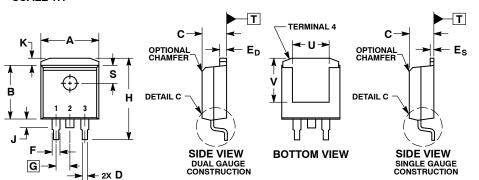
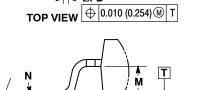




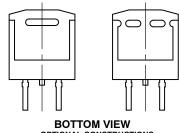
D²PAK CASE 936-03 **ISSUE E**

DATE 29 SEP 2015





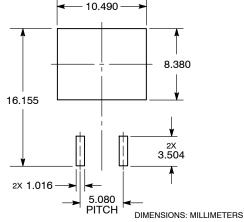
DETAIL C



OPTIONAL CONSTRUCTIONS

RECOMMENDED SOLDERING FOOTPRINT*

SEATING PLANE



*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

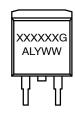
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCHES. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS

- A AND K.
 DIMENSIONS U AND V ESTABLISH A MINIMUM
- MOUNTING SURFACE FOR TERMINAL 4.

 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD
- FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.
- SINGLE GAUGE DESIGN WILL BE SHIPPED AF-TER FPCN EXPIRATION IN OCTOBER 2011.

		HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.386	0.403	9.804	10.236	
В	0.356	0.368	9.042	9.347	
С	0.170	0.180	4.318	4.572	
D	0.026	0.036	0.660	0.914	
ED	0.045	0.055	1.143	1.397	
Es	0.018	0.026	0.457	0.660	
F	0.051	REF	1.295 REF		
G	0.100	BSC	2.540 BSC		
Н	0.539	0.579	13.691	14.707	
J	0.125	0.125 MAX		3.175 MAX	
K	0.050	REF	1.270 REF		
L	0.000	0.010	0.000	0.254	
M	0.088	0.102	2.235	2.591	
N	0.018	0.026	0.457	0.660	
P	0.058	0.078	1.473	1.981	
R	0°	8°	0°	8°	
S	0.116 REF		2.946 REF		
U	0.200 MIN		5.080 MIN		
V	0.250 MIN		6 350 MIN		

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location

= Wafer Lot 1 = Year Υ ww = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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